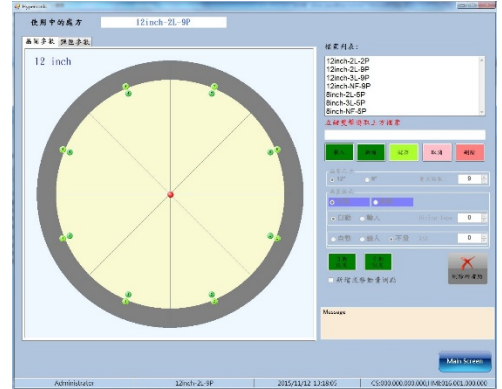


Features

- Granite base Stage
- Auto Cassette Load / Unload port
- Auto X-Y table
- Auto thickness measurement
- Measuring locations programmable
- High accuracy laser sensor
- Wafer size capability: 8", 12"
- Thickness range: 25um to 1500um
- Working type: Wafer with frame



Measuring items

Wafer:

- TTV. (Total thickness variation)
- Average
- Max/Min
- Dicing tape
- Average thickness



WFSCAN-20 Specification		
<i>Item</i>	<i>Stage Specification</i>	
1	Measurement area (X * Y)	350 X 350 [mm]
2	Linear motor encoder resolution	1 um/pulse
3	Travel limit in Z direction	Manual adjustment
<i>Item</i>	<i>Laser sensor Specification</i>	
1	Laser sensor resolution	0.3 um
2	Measurement Range (Z direction)	25um to 1500um
3	Thickness measuring accuracy	+/- 3um
<i>Item</i>	<i>Wafer Handling</i>	
1	Working type	Wafer with frame
2	Wafer size capability	8"; 12"
3	Load port	Single 8" ,12" wafer cassette load-port
4	Handling	P&P arm with vacuum cup
<i>Item</i>	<i>System Dimension</i>	
1	Dimensions (L x W x H)	1900 mm x 1600 mm x 1800 mm
2	Wieght	1200 Kg